



## Description

The HSBA8016 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

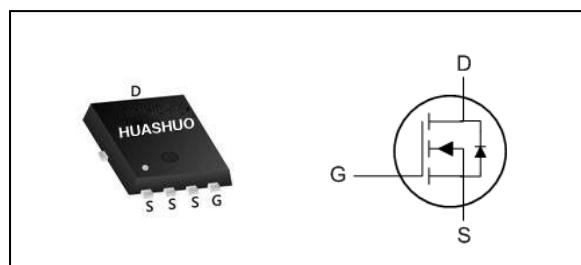
The HSBA8016 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

V <sub>DS</sub>	80	V
R <sub>DS(ON),max</sub>	12	mΩ
I <sub>D</sub>	62	A

## PRPAK5X6 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	80	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current <sub>1</sub>	62	A
I <sub>D</sub> @T <sub>c</sub> =70°C	Continuous Drain Current <sub>1</sub>	49	A
I <sub>DM</sub>	Pulsed Drain Current <sub>2</sub>	200	A
EAS	Single Pulse Avalanche Energy <sub>3</sub>	80	mJ
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sub>4</sub>	89	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sub>1</sub>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sub>1</sub>	---	1.3	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	80	---	---	V
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sub>2</sub>	V <sub>GS</sub> =10V , I <sub>D</sub> =10A	---	9.6	12	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A	---	12	14.5	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	---	2.5	V
I <sub>bss</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =64V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =64V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
I <sub>GS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fS</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A	---	32	---	S
R <sub>G</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	0.66	---	Ω
Q <sub>g</sub>	Total Gate Charge (10V)	V <sub>DS</sub> =64V , V <sub>GS</sub> =10V , I <sub>D</sub> =4A	---	60.9	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	8.1	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	17.9	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =40V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω, I <sub>D</sub> =4A	---	12.2	---	ns
T <sub>r</sub>	Rise Time		---	24.5	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	50.5	---	
T <sub>f</sub>	Fall Time		---	17.6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz	---	3120	---	pF
C <sub>oss</sub>	Output Capacitance		---	140	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	110	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current <sub>1,5</sub>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	62	A
V <sub>SD</sub>	Diode Forward Voltage <sub>2</sub>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =4A , dI/dt=100A/μs , T <sub>J</sub> =25°C	---	18.6	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	65	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup>FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=50V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



Typical Characteristics

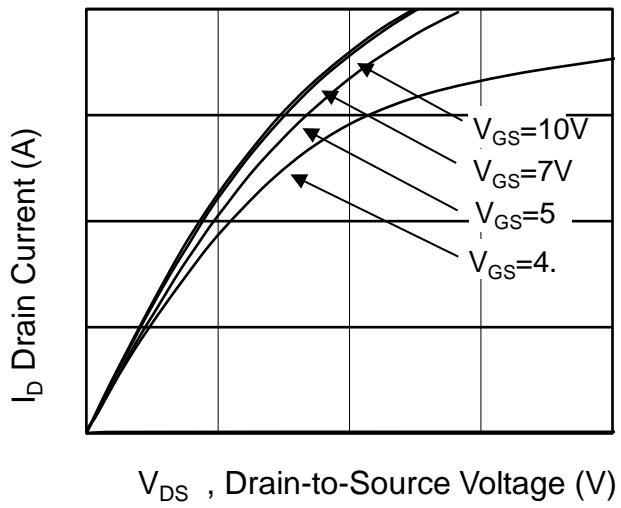


Fig.1 Typical Output Characteristics

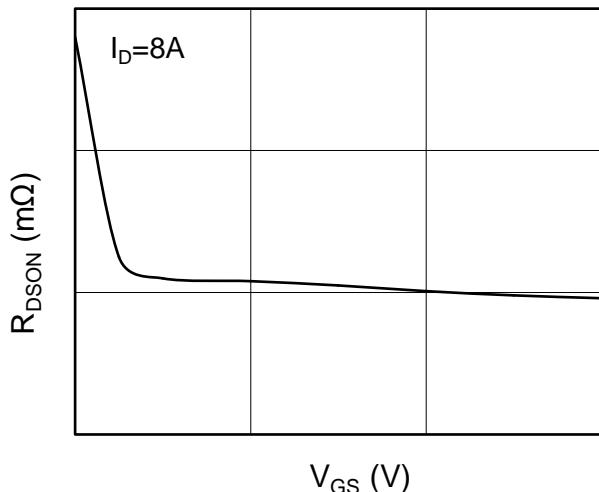


Fig.2 On-Resistance vs. Gate-Source Voltage

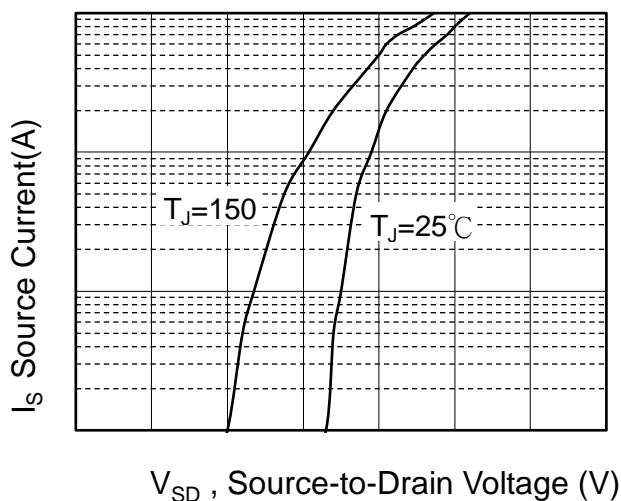


Fig.3 Forward Characteristics of Reverse

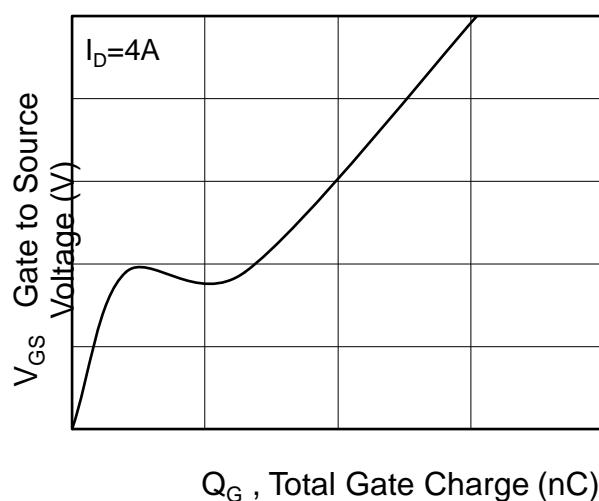


Fig.4 Gate-Charge Characteristics

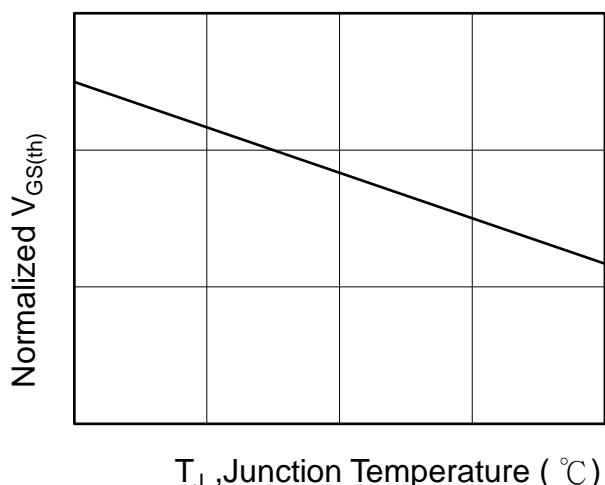


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

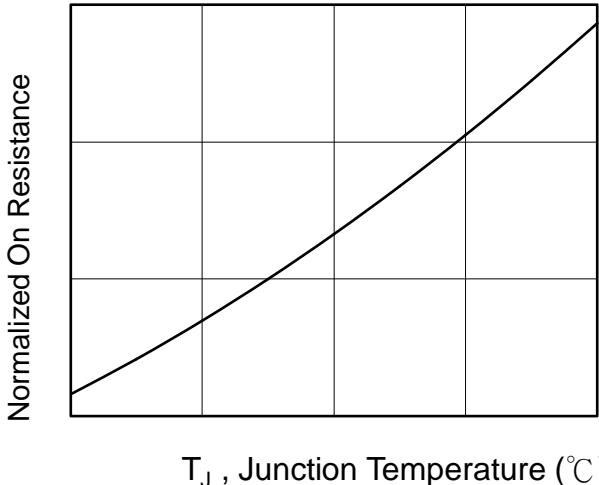
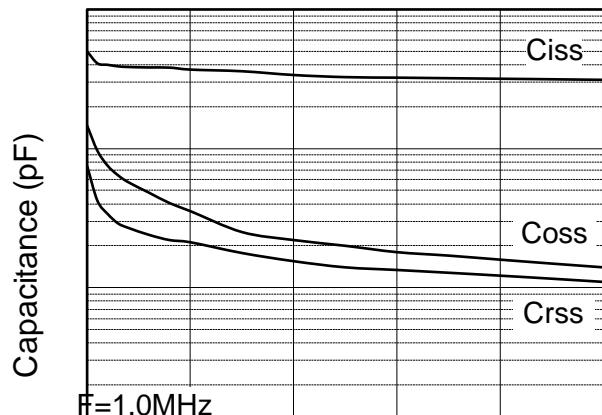
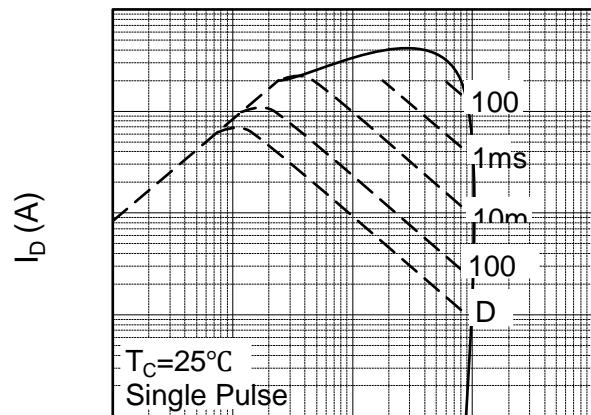


Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$



$V_{DS}$  Drain to Source Voltage(V)



$V_{DS}$  (V)

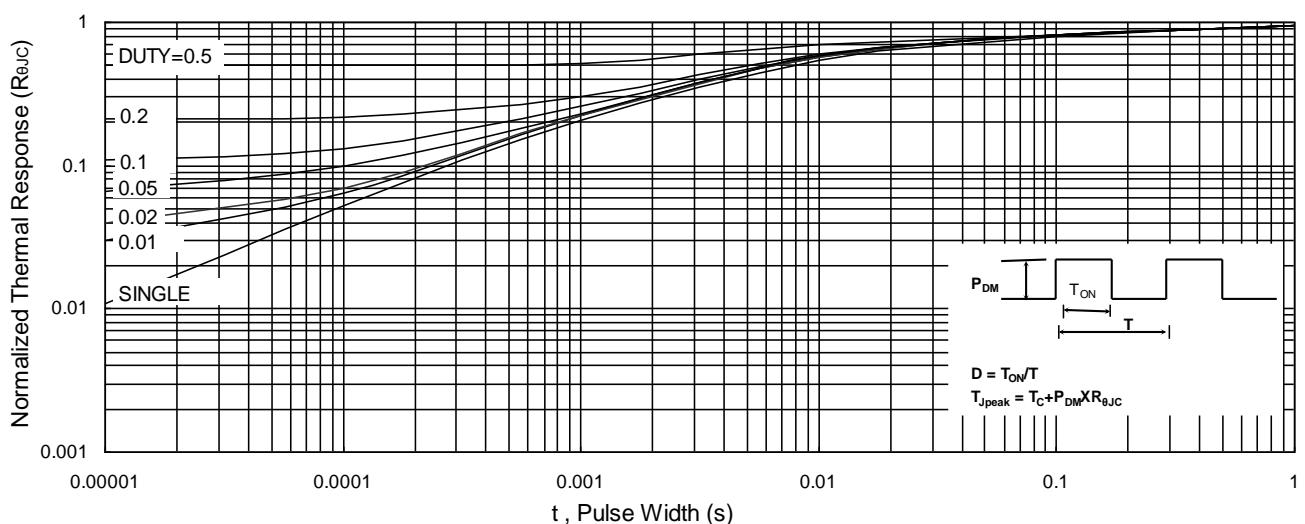


Fig.9 Normalized Maximum Transient Thermal Impedance

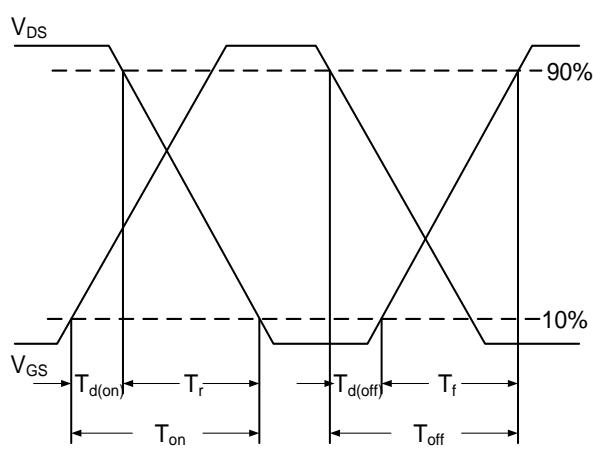


Fig.10 Switching Time Waveform

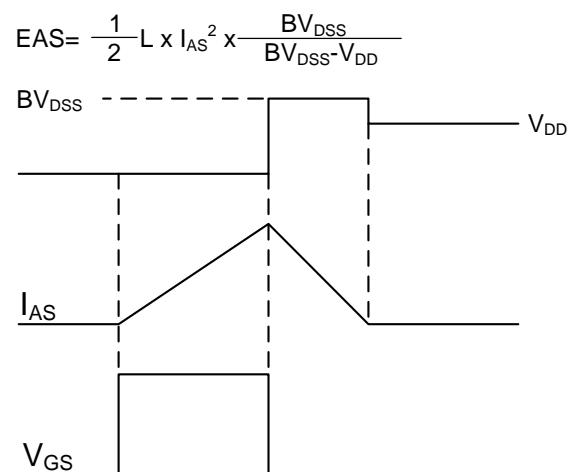


Fig.11 Unclamped Inductive Switching



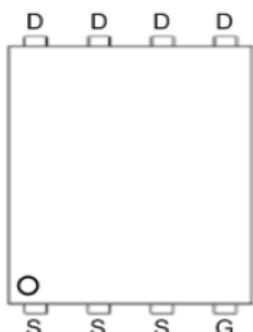
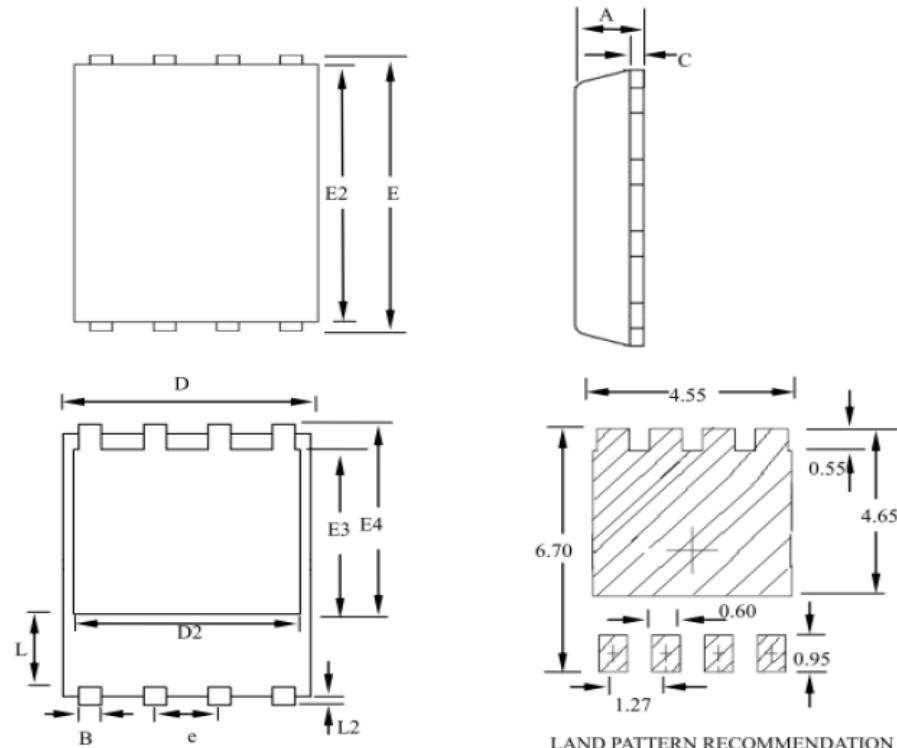
**HUASHUO**  
SEMICONDUCTOR

**HSBA8016**

**N-Ch 80V Fast Switching MOSFETs**

## Ordering Information

Part Number	Package code	Packaging
HSBA8016	PRPAK5*6	3000/Tape&Reel



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145	--	0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--